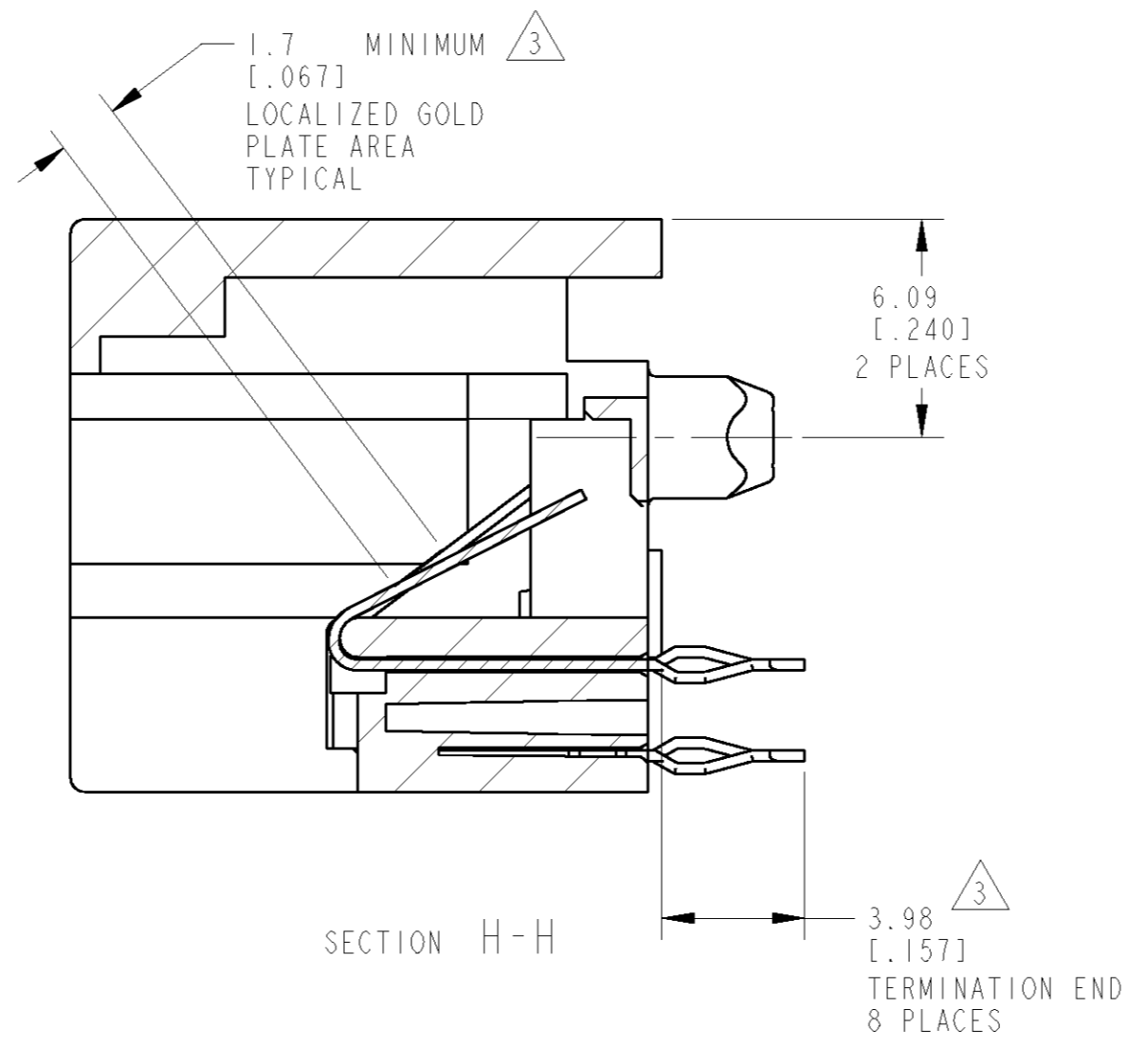
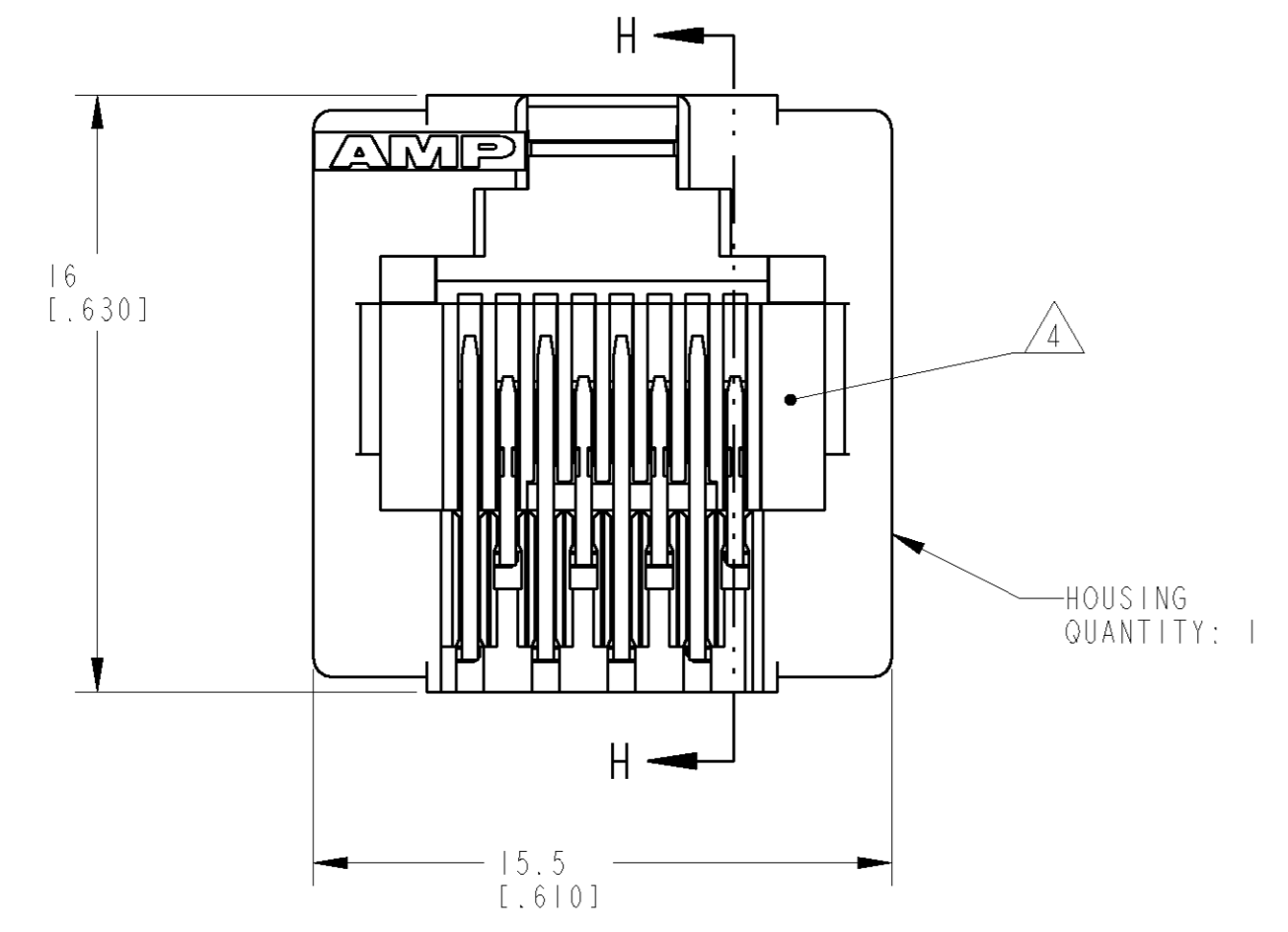
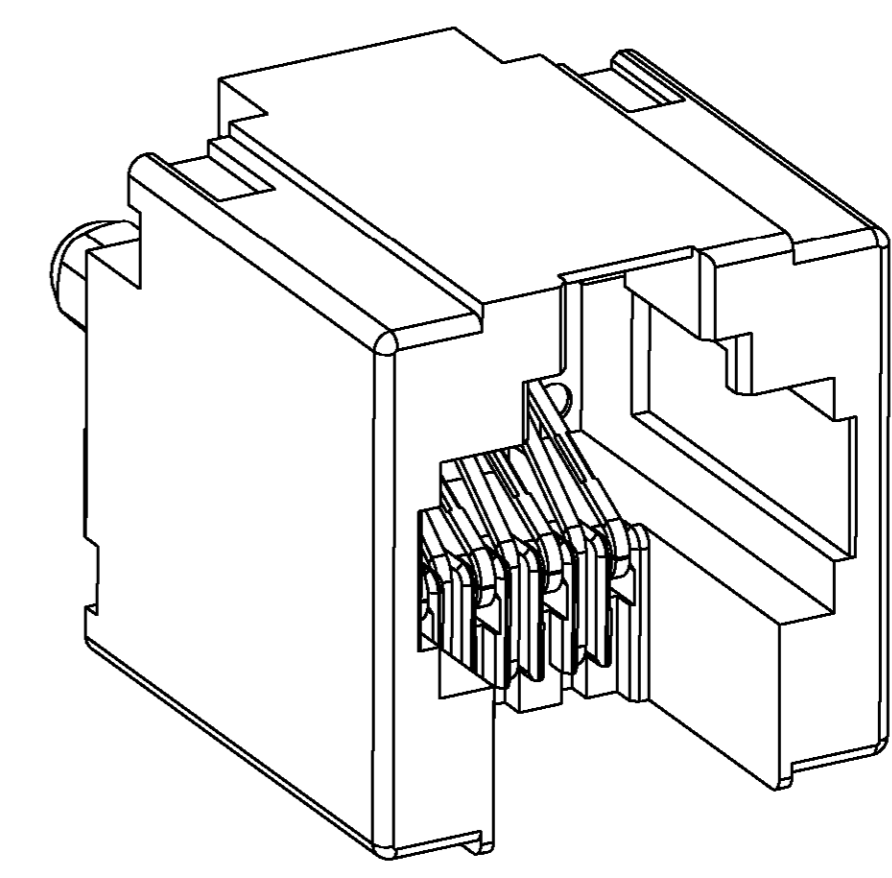
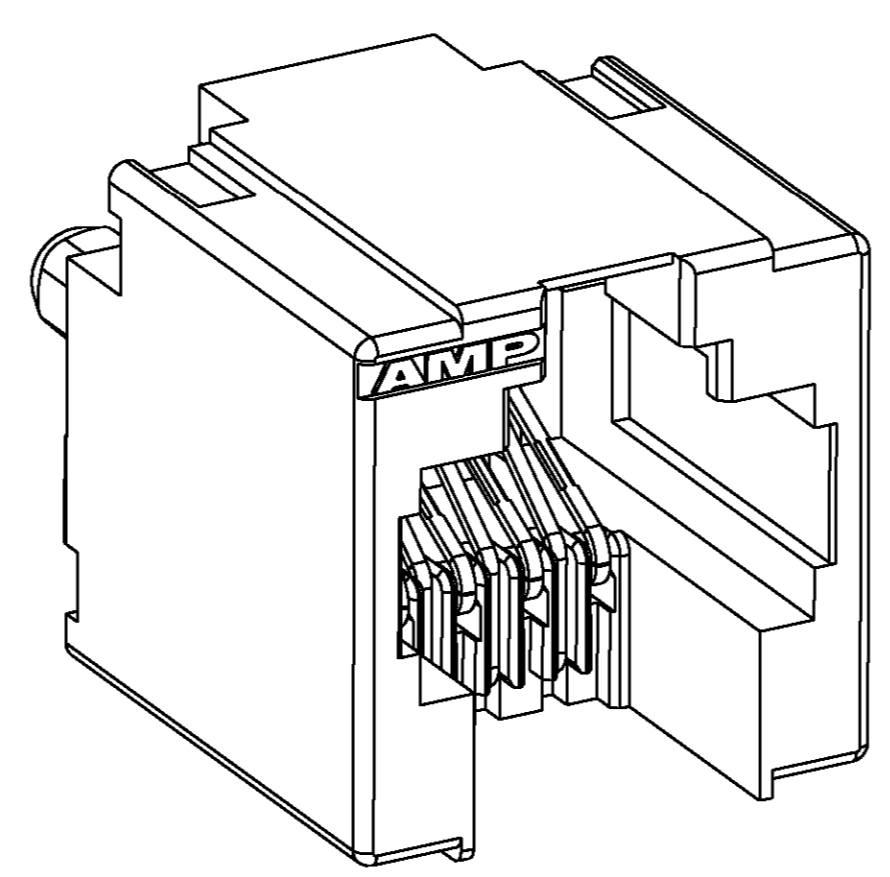
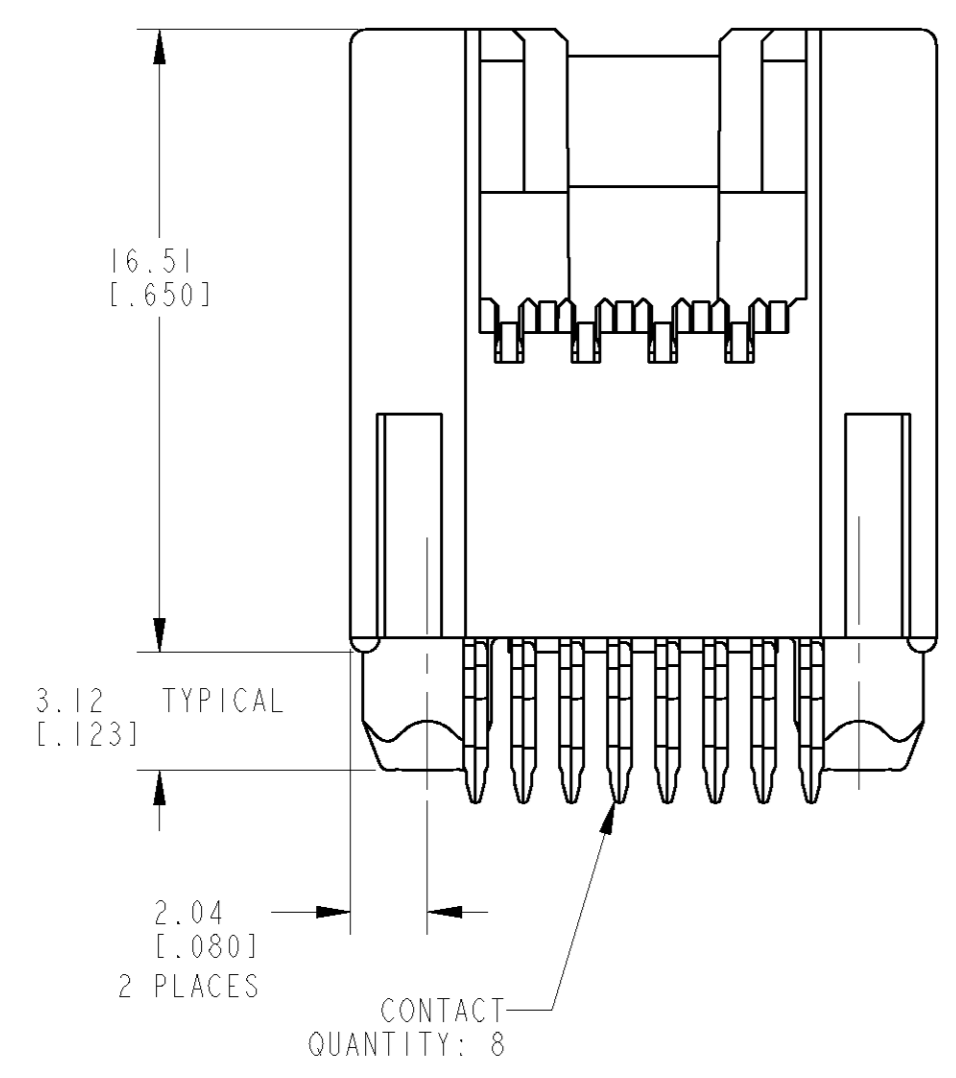


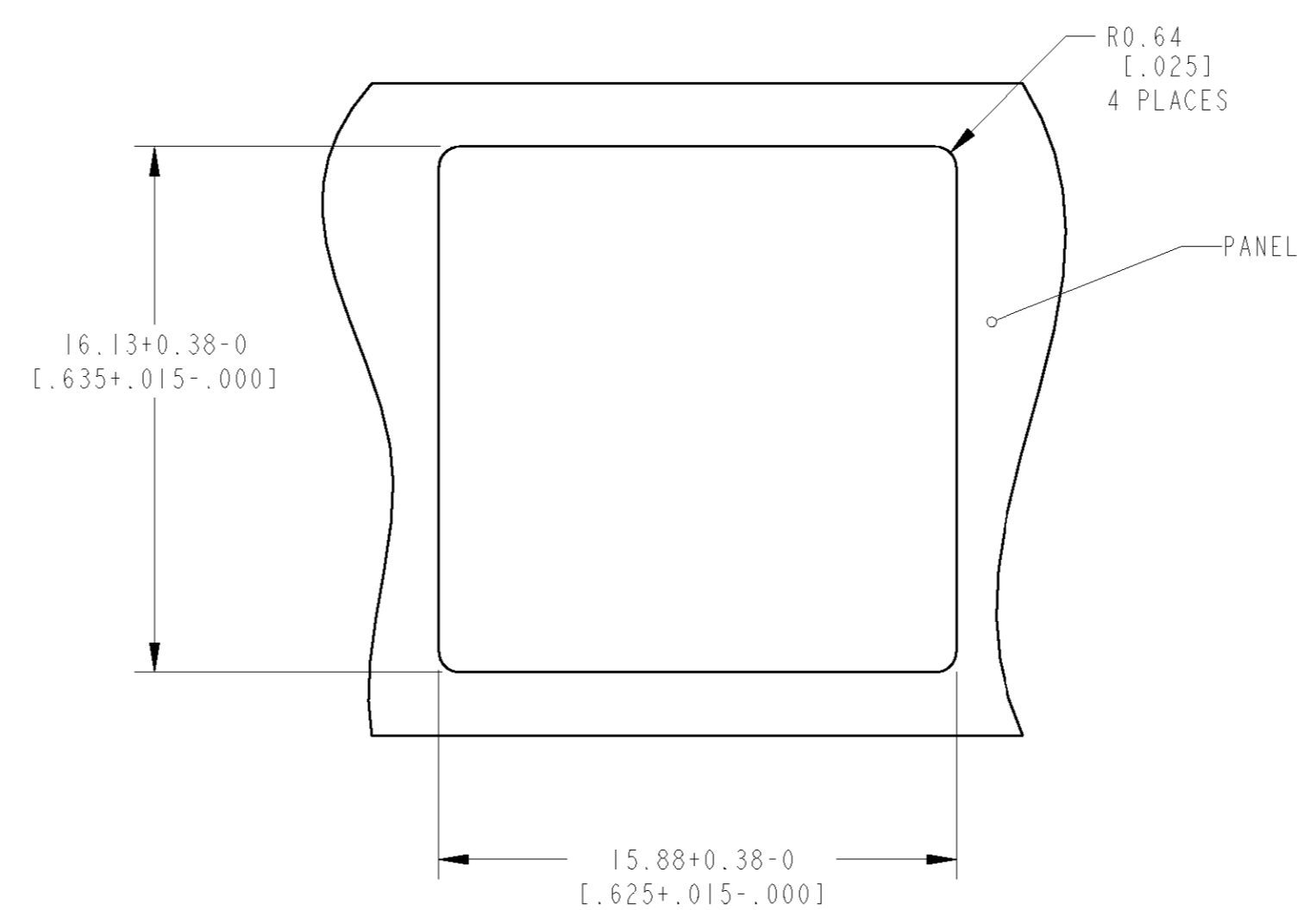
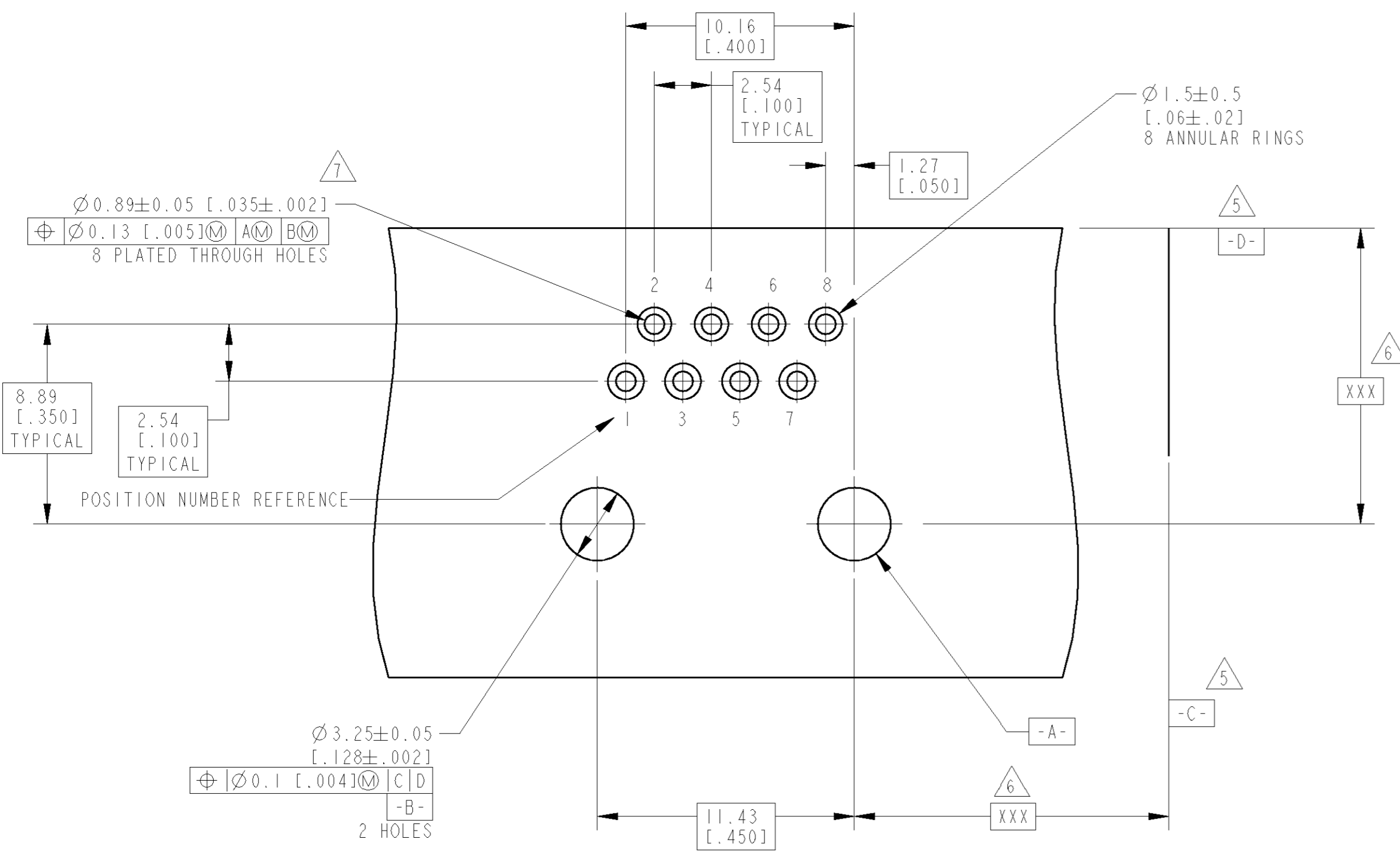
LOC	DIST	REVISIONS			
F	LTR	DESCRIPTION	DATE	DWN	APPD
D		REVISED PER EC 0UF0-0071-01	31MAY2001	JA	LLV
E		REVISED PER EC 0S11-0019-03	20MAR2003	DD	BK
F		ADDED: -2 PER EC 0S11-0054-03	20MAR2003	DD	BK



- 1 THERMOPLASTIC, COLOR-BLACK.
- 2 PHOSPHOR BRONZE
- 3 1.27µm [0.00050] MIN GOLD IN LOCALIZED GOLD PLATE AREA, 2µm [0.00079] MIN TIN-LEAD ON TERMINATION END, BOTH OVER 1.27µm [0.00050] MIN NICKEL.
- 4 CAVITY CONFORMS TO FCC 47 CFR 68 PART F.
- 5 DATUMS ESTABLISHED BY CUSTOMER.
- 6 DIMENSIONS ESTABLISHED BY CUSTOMER.
- 7 DRILLED HOLE DIAMETER 1.02±0.03 [0.040.001], COPPER THK 0.03-0.08 [0.001-.003], TIN-LEAD THICKNESS 8µm [0.000315] MIN.
- 8 PC BOARDS GREATER THAN 1.57 [0.062] IN THICKNESS MAY REQUIRE SPECIAL EXTRACTION TOOLING, CONSULT ENGINEERING.



1116201-2 SHOWN  
(WITH NO "AMP" LOGO)



RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT  
 RECOMMENDED PRINTED CIRCUIT BOARD THICKNESS 1.42 [0.055] MIN  
 COMPONENT SIDE OF PRINTED CIRCUIT BOARD

NO "AMP" LOGO	1116201-2
AS SHOWN	1116201-1
DESCRIPTION	PART NUMBER

DIMENSIONS: mm [INCHES] TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ± 1 PLC ±0.13 [0.005] 2 PLC ± 3 PLC ± 4 PLC ± ANGLES ±		DWN J. AHERON 23APR99 CDR I. VARSIK 04MAY99 APD I. VARSIK 04MAY99 NAME: MODULAR JACK ASSEMBLY, VERTICAL, COMPLIANT PIN, 8 POSITION, CATEGORY 5 PRODUCT SPEC: 108-1163-6 APPLICATION SPEC: 114-2158 WEIGHT: - CUSTOMER DRAWING	
MATERIAL: HOUSING: 1 FINISH: - CONTACT: 2		AMP Incorporated Harrisburg, PA 17105-3608 SIZE: A11 00779 C=1116201 SCALE: 5:1 SHEET 1 OF 1 REV F	